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## ECE 4170: Introduction to Hardware Description Languages with Applications to Digital Design

Spring 2007

ECE 4170 (1)

## Course Content: Goals

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- Understand the concepts underlying hardware description languages
  - Roles and application in digital design flows
  - Key language features: what is represented and why
- Reinforce language concepts with a significant project component
  - Place the project in the context of modern system-on-chip design
- Use VHDL as the working language
  - Introduction to competing, alternative languages
  - Understand commonality with VHDL as well as rationale for their distinct language features

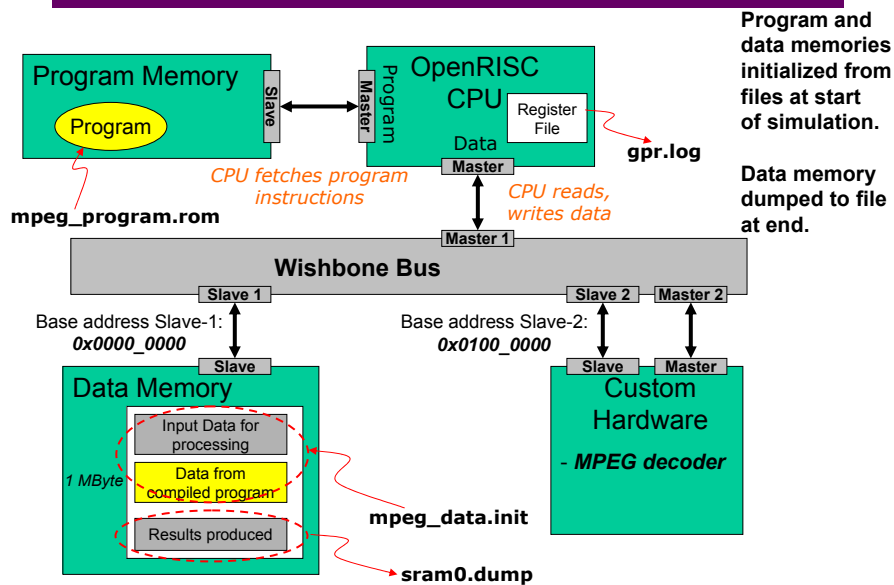
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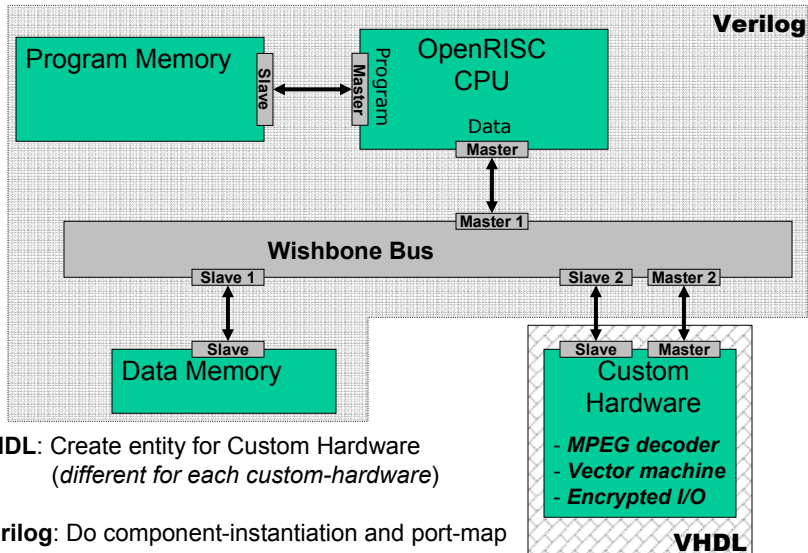
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## Course Content: Goals (cont.)


- Learn and apply industry standards
  - Open core protocol (OCP)
    - Standard for Intellectual property (IP) integration
    - SPIRIT: standard for describing IP metadata
  - 1076.6 IEEE Standard for VHDL RTL Synthesis
- System-on-Chip project infrastructure
  - Leverage available SoC infrastructures
    - OpenRISC
    - MicroBlaze

## System Architecture





- Escalating costs and time to market of silicon platforms
  - Mask costs
  - Manufacturing
  - Verification
  - Design
- Escalating design complexity
  - Number of transistors
  - Deep submicron effects
  - Application complexity in emerging markets
- Need for hardware customization
  - To concurrently meet physical, functional, and cost requirements

- Raise the level of design abstraction
  - Emergence of Electronic System Level (ESL) Design
    - Algorithm-based RTL synthesis
- Raise the level of hardware building blocks
  - Processors, memories, cores, etc.
  - Configurable fabrics
  - Emergence of System-on-Chip (SoC) platforms
- IP–Reuse 
  - In design: For example ARC, ARM and Artisan
  - In manufacturing: For example NEC and eASIC

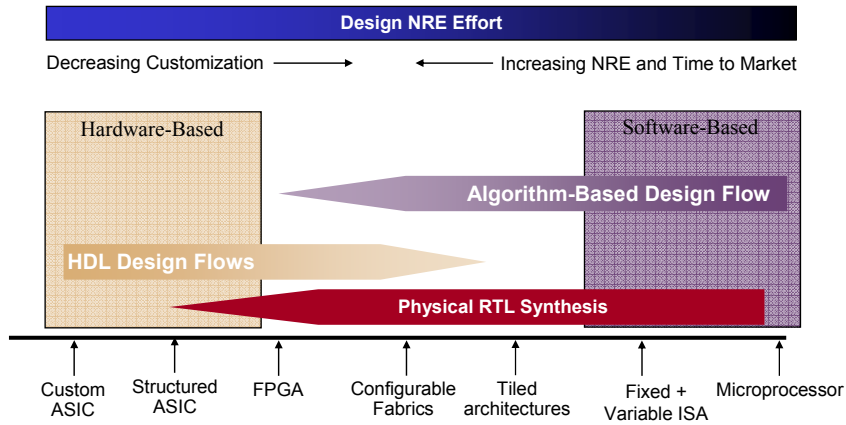
- Integration:
  - A byproduct of Moore's Law
- Manufacturing
  - Emergence of design for manufacturing
- Consolidation
  - Emergence of new design processes
- Costs

Design and IP will become the primary differentiators

- Emergence of derivative SoC Platforms
  - 10s of platforms but thousands of derivative platforms
  - Derivatives couple application specific logic with commodity component-based platforms
- Growth in consumer markets
  - OEMs need complete solutions to focus on product differentiation in short product development cycles
- Exploding pool of accessible embedded software developers
  - Access to geographically distributed SoC IP generation capability
- Fragmented derivative SoC development flow
  - Weak link between ESL and RTL for design
  - Fragmented software development tool chain and environment

Convergence of software development, hardware customization, & IP re-use

- Consumer
  - Home entertainment, cell phones, intelligent imaging, gaming
- Communications
  - Wireless, VoIP, video conferencing, cell phones
- Emphasis on power/performance balance
- New (commodity) design processes that
  - Make use of distributed intellectual capital → lower the expertise barrier
  - Collaboration (horizontal) is more important than top-down control (vertically directed) of design
  - Open source & standards (C, Spirit, OCP, etc) is the vehicle
  - Design/IP is the driver/differentiator rather than manufacturing

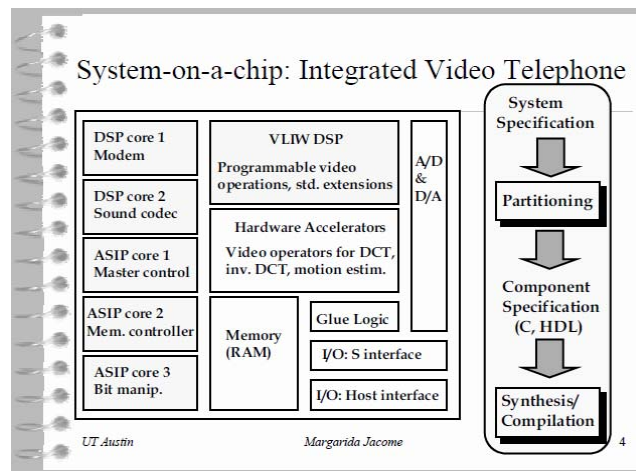


- ASICs will outgrow semiconductor industry 2006 (Gartner)
  - One-third will be structured ASICs by 2008
  - \$2B market by 2007
  - Altera and LSI Logic are market leaders
  - ~\$200M - \$300M tools market
- Electronic System Level (ESL) design tools will be \$1.6B by 2009 (Gartner)
  - Companies reliance in internal ESL tools increased 33% in 2005
- Capture 10%-20% of the FPGA market
  - ~\$5B in 2007

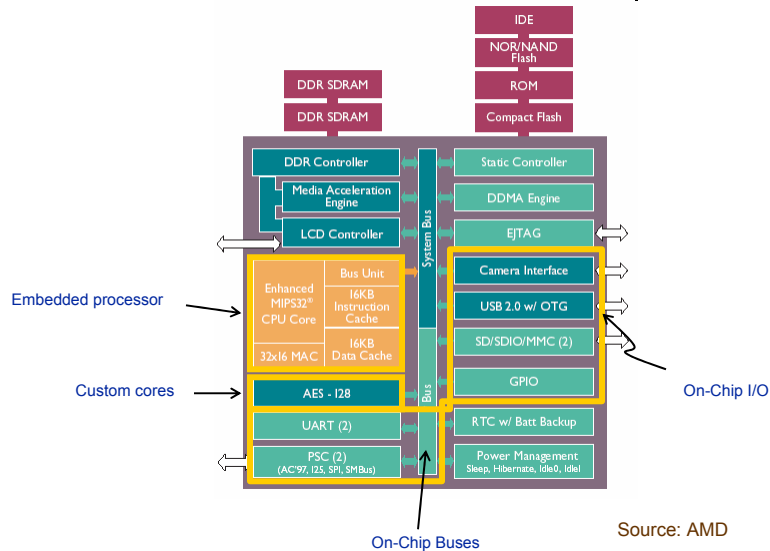
## The Challenge: SoC Design

- Modern System-on-Chip Design is dominated by intellectual property (IP) re-use
- Chip complexity is spread across multiple design groups in multiple companies, and even across multiple market segments
- Large fraction of time is spent on integration and testing → emergence of industry standards for IP integration

## Example



## AMD Au1200 System on Chip



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## Course Logistics

- Instructor: Professor Sudhakar Yalamanchili
  - Class webpage for contact information  
[www.ece.gatech.edu/users/sudha/4170/Spring2007](http://www.ece.gatech.edu/users/sudha/4170/Spring2007)
  - Recommended Text: *VHDL: From Simulation to Synthesis*, S. Yalamanchili, Prentice Hall (pubs.)
  - The following will be provided:
    - Class notes
    - Alternatives to the recommended text
    - Supplemental reading
- Teaching Assistant: TBA
- Infrastructure
  - ECE Linux Clusters in the College of computing building
    - Simulation: Modelsim
    - Synthesis: Mentor Graphics Leonardo Spectrum or Synplicity
  - Tutorials will be provided

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- Midterms: 2, 20% each
  - 24 hour take home examination
- Assignments: 20%
- Final/Project: 40%
  - Group projects will be considered
  - Detailed description of milestones will be provided
    - Schedule, format, and content
  - Presentation during final examination
  - Final oral examination